

Amendments to the Claims:

Claims 1-27 (Canceled)

28. **(New)** A component insertion method comprising:

at a component grasping position, releasably grasping a first component, having a device portion and a lead wire at said device portion, by applying a first grasping pressure to said first component;

while releasably grasping said first component, performing a first positional alignment in a direction along a surface of a board to align said lead wire of said first component and a first lead-wire insertion hole of said board;

after said performing of said first positional alignment, inserting said lead wire of said first component into said first lead-wire insertion hole of said board;

at said component grasping position, releasably grasping a second component, having a device portion and a lead wire at said device portion, by applying a second grasping pressure to said second component;

while releasably grasping said second component, performing a second positional alignment in a direction along said surface of said board to align said lead wire of said second component and a second lead-wire insertion hole of said board;

after said performing of said second positional alignment, inserting said lead wire of said second component into said second lead-wire insertion hole of said board;

wherein said device portion of said first component is lower in rigidity than said device portion of said second component; and

wherein said releasably grasping of said first component and said releasably grasping of said second component are carried out such that said first grasping pressure applied to said first component is lower than said second grasping pressure applied to said second component.

29. **(New)** The component insertion method according to claim 28, wherein

said inserting of said lead wire of said first component into said first lead-wire insertion hole of said board comprises

(i) with said first component being releasably grasped, engaging an end portion of said lead wire of said first component with an engagement portion of a guide pin extending through said first lead-wire insertion hole,

(ii) using a pusher to apply a first pressing pressure to press said device portion of said first component toward an insertion position of said board such that engagement is maintained between said guide pin and said lead wire of said first component, and

(iii) while the engagement between said guide pin and said lead wire of said first component is maintained, discontinuing the releasably grasping of said first component and using said guide pin to guide said lead wire of said first component into said first lead-wire insertion hole; and

said inserting of said lead wire of said second component into said second lead-wire insertion hole of said board comprises

(i) with said second component being releasably grasped, engaging an end portion of said lead wire of said second component with an engagement portion of a guide pin extending through said second lead-wire insertion hole,

(ii) using a pusher to apply a second pressing pressure to press said device portion of said second component toward an insertion position of said board such that engagement is maintained between said guide pin and said lead wire of said second component, and

(iii) while the engagement between said guide pin and said lead wire of said second component is maintained, discontinuing the releasably grasping of said second component and using said guide pin to guide said lead wire of said second component into said second lead-wire insertion hole; and

said first pressing pressure applied to press said device portion of said first component is less than said second pressing pressure applied to press said device portion of said second component.

30. **(New)** The component insertion method according to claim 29, further comprising:

after said lead wire of said first component has been guided into said first lead-wire insertion hole, fixing said first component to said board by bending said lead wire of said first component while said pusher member presses said device portion of said first component such that said device portion of said first component is held at the insertion position, with a pressure applied for pressing said device portion such that said device portion is held at the insertion position being greater than the pressure applied for maintaining engagement between the engagement portion of the guide pin and said lead wire of said first component; and

after said lead wire of said second component has been guided into said second lead-wire insertion hole, fixing said second component to said board by bending said lead wire of said second component while said pusher member presses said device portion of said second component such that said device portion of said second component is held at the insertion position, with a pressure applied for pressing said device portion such that said device portion is held at the insertion position being greater than the pressure applied for maintaining engagement between the engagement portion of the guide pin and said lead wire of said second component.

31. **(New)** The component insertion method according to claim 30, further comprising:

using the pusher member to press and hold a third component at an insertion position of the board while a lead wire of said third component extends through a third lead-wire insertion hole of said board, with said lead wire of said third component being greater in rigidity than said lead wire of said first component and said lead wire of said second component,

wherein a pressure applied for pressing and holding said third component at the insertion position is greater than the pressure applied for pressing said device portion of said first

component such that said device portion is held at the insertion position, and greater than the pressure applied for pressing said device portion of said second component such that said device portion is held at the insertion position.

32. **(New)** The component insertion method according to claim 28, wherein

said first grasping pressure is a pressure which permits grasping and holding of said device portion of said first component without plastically deforming a configuration of said device portion of said first component, and

said second grasping pressure is a pressure which permits grasping and holding of said device portion of said second component without plastically deforming a configuration of said device portion of said second component.

33. **(New)** The component insertion method according to claim 29, wherein

said first pressing pressure is a pressure which permits pressing of said device portion of said first component without plastically deforming a configuration of said device portion of said first component, and

said second pressing pressure is a pressure which permits pressing of said device portion of said second component without plastically deforming a configuration of said device portion of said second component.

34. **(New)** The component insertion method according to claim 28, wherein said first and second components comprise radial components, respectively, said method further comprising

for at least one of said first and second components, correcting an insertion posture of the component prior to said inserting of the lead wire of the component into the respective one of the first and second lead-wire insertion holes,

wherein said correcting of the insertion posture of the component includes grasping said lead wire of said component and performing positional alignment in a direction along a surface

of the board between the lead wire of the component and the respective lead-wire insertion hole of the board, and along with said grasping of said lead wire of said component, grasping the device portion of the component whose lead wire has been grasped to correct a bend of the lead wire on a fulcrum given by the grasping position of the lead wire so that the device portion is placed at the component insertion position in the direction along the surface of the board.

35. **(New)** The component insertion method according to claim 34, wherein

after the correction of the insertion posture of the component, an end portion of the lead wire of the component is held by a guide pin through the insertion hole of the board, and the grasping of the device portion and the grasping of the lead wire are released; and

the guide pin is moved so that the end portion of the lead wire is guided to the insertion hole of the board, thereby inserting the lead wire of the component into the insertion hole.

36. **(New)** The component insertion method according to claim 34, wherein

each of the components that are radial components has a plurality of the lead wires formed so as to be arrayed in one line, and

the correction of the insertion posture of the component is performed by moving the device portion in a direction extending along a surface of the board and generally perpendicular to the array direction of the lead wires.